

# AIXTRON five-year record

AIXTRON AG's latest financial results show the Aachen-based company is in confident mood. Equipment order intake was up 59% year-on-year and its gross margin was up 7% points year-on-year to 37%.

Improved market confidence saw equipment order intake increase substantially year-on-year, by 59% to €81.2m in the first six months of 2006, including €19.2m in orders received for silicon semiconductor equipment, or 24% of total equipment order intake. Moreover, order intake for compound equipment rose significantly, by 62% year-on-year, to €62.0m in the first six months of 2006, or 76% of total equipment order intake for the reported period.

Paul Hyland, CEO at AIXTRON, said: "Equipment order intake in the second quarter of 2006, at €49.5m, is the highest recorded equipment order intake figure for five years, and is 74% higher than in the second quarter of 2005. At €81.2m as of June 30, 2006, our equipment order backlog has risen by 55% year-over-year and is at its highest level since the third quarter of 2004."

He continued: "Genus has been fully integrated into the AIXTRON Group since the beginning of the year, and is now making a pleasingly consistent contribution to AIXTRON's business development."

For more details, visit: [www.aixtron.com](http://www.aixtron.com)

# JPSA offers 300mm silicon wafer singulation capability

The new ChromaDice UV-DPSS laser systems from J.P. Sercel Associates can now scribe and dice 300mm wafers, up to 500 microns thick. Other versions with short pulse UV lasers offer high speed, high yield processing of sapphire, silicon and GaAs wafers, as well as other materials.

The UV laser process is a fast, low-stress method of singulation that minimizes chip breakage after cutting, for higher yields, and generates minimal debris. The UV singulation process is vibration-free, unlike processing with a mechanical dicing saw.

Jeffrey P. Sercel, President, said: "With this new, larger wafer handling capability, customers can realize high yields and high-speed processing as well as increased process efficiency. Our patented ChromaDice system will singulate wafers up to 500

microns thick, so we're not limited to thin wafers. Since there is little or no heat affected zone, cuts are clean and stress-free, for higher die count per wafer than traditional scribing methods, as well as greater than 99% yield for better economic payback."

JPSA ChromaDice systems feature high-performance, ultra-precise air bearing stages that provide higher speed and acceleration in addition to greater travel for up to 300mm wafers. The system is also available with either 355nm or 266nm high-power, short pulse UV lasers for high speed, high yield processing of sapphire, silicon and GaAs wafers, as well as other materials. The 300mm processing systems are available with complete wafer handling systems including cassette loading.

For more details, visit: [www.jpsalaser.com](http://www.jpsalaser.com)